

MICA RoHS Compliance Worksheet

Series or Type	Description or Photo	RoHS Compliance Identification on Device	Termination Finish	PB Free	RoHS Compliant	Compliant Part Number	Package Marking	Date Compliant	Moisture Sensitivity Level (IPC/JEDEC J-STD-020C)	Soldering Conditions (Temp/Time)	Notes
CD (except as noted below)	Silvered Dipped Mica	mustard color	Sn	<1000 PPM	Y	add letter F after	PER JESD97	2/1/2006	N/A	260°C/10s	clamped leads so no problem with tin foil
CD6, CD7	Silvered Dipped Mica	N/A	Sn	N	N	N/A	N/A	N/A	N/A	260°C/10s	lead solder required to attach leads to lead foil section
CDB, CDVB	Metallurgical Bonded Ag Dipped Mica	N/A	Sn40Pb	N	N	N/A	N/A	N/A	N/A	260°C/10s	Requires Lead foil in order to metallurgically bond successfully
CM0, CMR	Silvered Dipped Mica	N/A	Sn40Pb	N	N	N/A	N/A	N/A	N/A	260°C/10s	Military part and must contain PB in leads
MC	SMT Mica Chip	N	Sn	>1000 PPM*	Y	add suffix -F	PER JESD97	3/25/2005	MSL2A	220-260/10s	
MCH, MCN	SMT nonmagnetic mica chip	N	Sn	>1000 PPM*	Y	always been compliant	PER JESD97	ALWAYS	MSL2A	220-260/10s	
MIN	SMT Metal Clad Mica	N/A	Ag	<1000 PPM	Y	add suffix -F	PER JESD97	1/1/2006	N/A	260°C/10s	
MCM	Metal Clad Mica	N/A	Ag	<1000 PPM	Y	add suffix -F	PER JESD97	1/1/2006	N/A	260°C/10s	

Revise on 06/11/18

* subject to exemption #7(c)I

To the best of our knowledge, the information provided on the enclosed is correct as of the date indicated on the document. Since some of the information is provided by the acceptance of data from sources outside of Cornell Dubilier Electronics, we can not guarantee that all is complete and accurate.